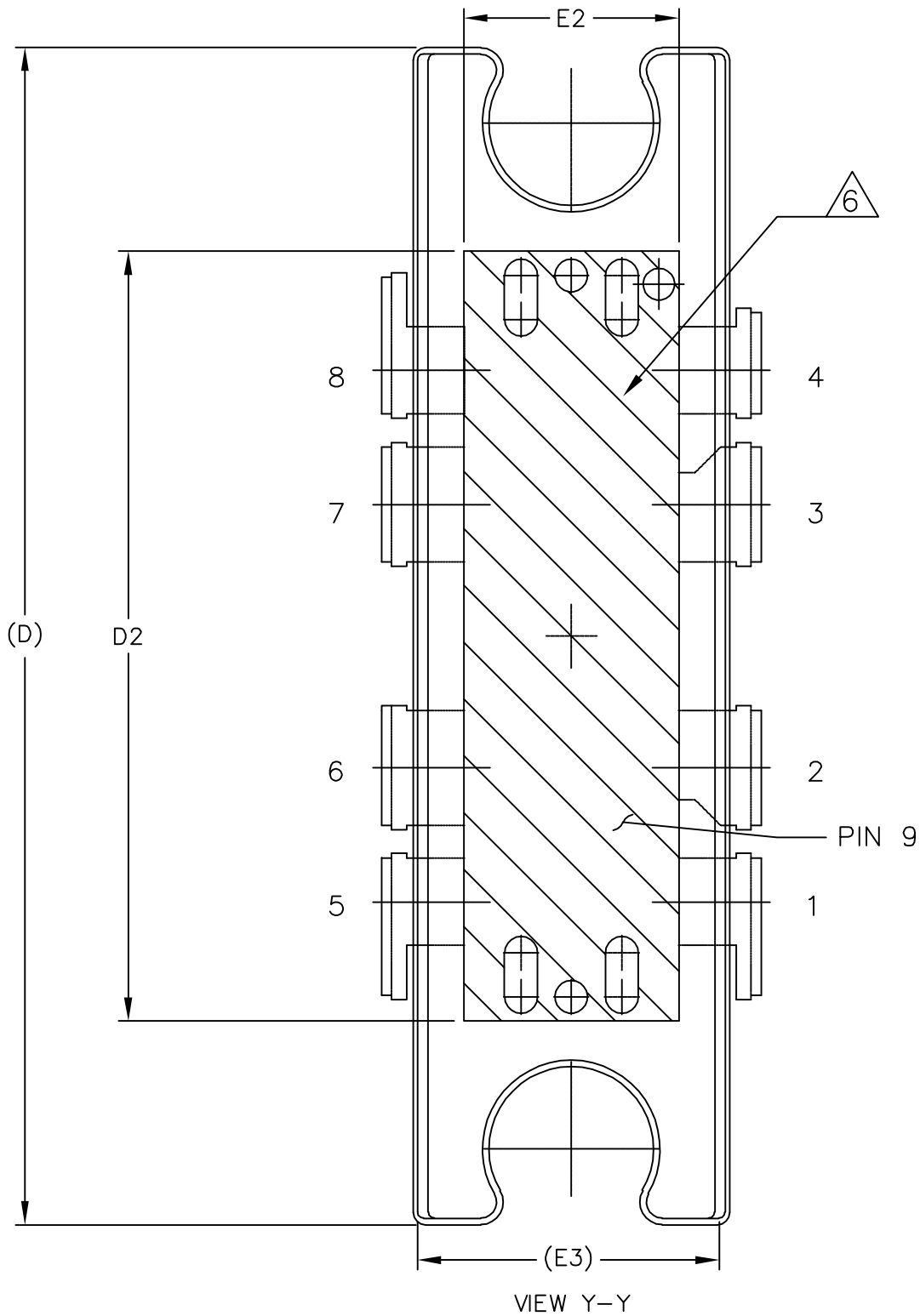


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TITLE:  TO-272, SPLIT LEAD	DOCUMENT NO: 98ASA99295D	REV: F
	STANDARD: NON-JEDEC	
	SOT1741-1	22 JAN 2016



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NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.

4. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.

5. DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE DIMENSIONS AT MAXIMUM MATERIAL CONDITION.

6. CROSSHATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

STYLE 1:

PIN 1 - SOURCE (COMMON)	PIN 5 - SOURCE (COMMON)
PIN 2 - DRAIN	PIN 6 - GATE
PIN 3 - DRAIN	PIN 7 - GATE
PIN 4 - SOURCE (COMMON)	PIN 8 - SOURCE (COMMON)
	PIN 9 - SOURCE (COMMON)

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.098	.108	2.49	2.74	b1	.088	.094	2.24	2.39
A1	.000	.004	0.000	0.10	b2	.066	.072	1.68	1.83
A2	.100	.104	2.54	2.64	b3	.067	.073	1.70	1.85
D	.928	.932	23.57	23.67	c1	.007	.011	0.178	0.279
D1	.810 BSC		20.57 BSC		e	.104 BSC		2.64 BSC	
D2	.604	----	15.34	----	e1	.210 BSC		5.33 BSC	
E	.296	.304	7.52	7.72	θ	0°	6°	0°	6°
E1	.248	.252	6.30	6.40	aaa	.004		0.1	
E2	.162	----	4.11	----					
E3	.241	.245	6.12	6.22					
L	.060	.070	1.52	1.78					
P	.126	.134	3.20	3.40					

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